

MOS FIELD EFFECT TRANSISTOR

2SK3984

SWITCHING

N-CHANNEL POWER MOSFET

DESCRIPTION

The 2SK3984 is N-channel MOS Field Effect Transistor designed for high speed switching applications such as class-D amplifier.

ORDERING INFORMATION

PART NUMBER	PACKAGE
2SK3984-ZK	TO-252 (MP-3ZK)

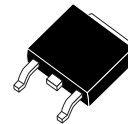
FEATURES

- Super low on-state resistance
 $R_{DS(on)} = 71 \text{ m}\Omega$ TYP. ($V_{GS} = 10 \text{ V}$, $I_D = 9 \text{ A}$)
 $R_{DS(on)} = 85 \text{ m}\Omega$ MAX. ($V_{GS} = 10 \text{ V}$, $I_D = 9 \text{ A}$)
- Low C_{iss} : $C_{iss} = 750 \text{ pF}$ TYP.

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$)

Drain to Source Voltage ($V_{GS} = 0 \text{ V}$)	V_{DSS}	100	V
Gate to Source Voltage ($V_{DS} = 0 \text{ V}$)	V_{GSS}	± 20	V
Drain Current (DC) ($T_C = 25^\circ\text{C}$)	$I_{D(DC)}$	± 18	A
Drain Current (pulse) ^{Note1}	$I_{D(pulse)}$	± 45	A
Total Power Dissipation ($T_C = 25^\circ\text{C}$)	P_{T1}	30	W
Total Power Dissipation ($T_A = 25^\circ\text{C}$)	P_{T2}	1.0	W
Channel Temperature	T_{ch}	150	$^\circ\text{C}$
Storage Temperature	T_{stg}	-55 to +150	$^\circ\text{C}$
Single Avalanche Energy ^{Note2}	E_{AS}	10	mJ
Repetitive Avalanche Current ^{Note3}	I_{AR}	10	A
Repetitive Avalanche Energy ^{Note3}	E_{AR}	10	mJ

(TO-252)



THERMAL RESISTANCE

Channel to Case Thermal Resistance	$R_{th(ch-C)}$	125	$^\circ\text{C/W}$
Channel to Ambient Thermal Resistance	$R_{th(ch-A)}$	4.17	$^\circ\text{C/W}$

Notes 1. $PW \leq 10 \mu\text{s}$, Duty Cycle $\leq 1\%$

2. Starting $T_{ch} = 25^\circ\text{C}$, $V_{DD} = 50 \text{ V}$, $R_G = 25 \Omega$, $V_{GS} = 20 \rightarrow 0 \text{ V}$, $L = 100 \mu\text{H}$

3. $T_{ch(peak)} \leq 150^\circ\text{C}$, $R_G = 25 \Omega$

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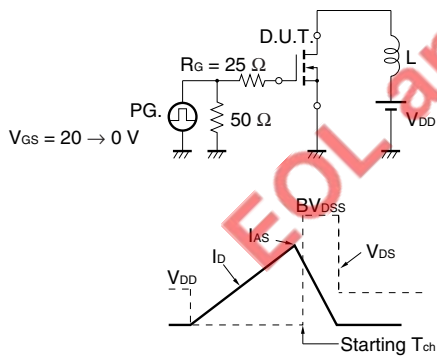
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ELECTRICAL CHARACTERISTICS (T_A = 25°C)

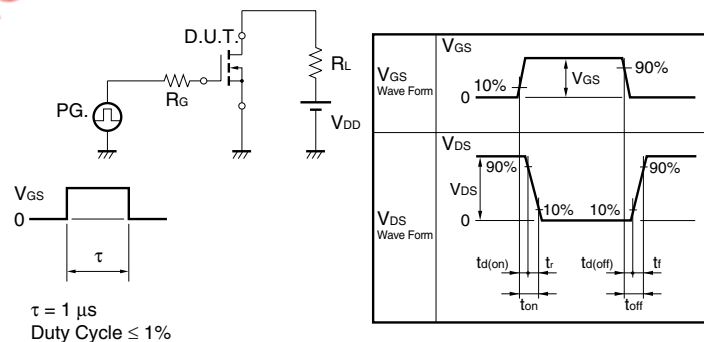
CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 100 V, V _{GS} = 0 V			10	μA
Gate Leakage Current	I _{GSS}	V _{GS} = ±20 V, V _{DS} = 0 V			±10	μA
Gate Cut-off Voltage	V _{GS(off)}	V _{DS} = 10 V, I _D = 1 mA	4.5	5.5	6.5	V
Forward Transfer Admittance Note	y _{fs}	V _{DS} = 10 V, I _D = 9 A	2.5	5.8		S
Drain to Source On-state Resistance Note	R _{DS(on)}	V _{GS} = 10 V, I _D = 9 A		71	85	mΩ
Input Capacitance	C _{iss}	V _{DS} = 10 V		750		pF
Output Capacitance	C _{oss}	V _{GS} = 0 V		120		pF
Reverse Transfer Capacitance	C _{rss}	f = 1 MHz		40		pF
Turn-on Delay Time	t _{d(on)}	V _{DD} = 50 V, I _D = 9 A		15		ns
Rise Time	t _r	V _{GS} = 10 V		6		ns
Turn-off Delay Time	t _{d(off)}	R _G = 10 Ω		17		ns
Fall Time	t _f			5		ns
Total Gate Charge	Q _G	V _{DD} = 50 V		13		nC
Gate to Source Charge	Q _{GS}	V _{GS} = 10 V		5.5		nC
Gate to Drain Charge	Q _{GD}	I _D = 18 A		4		nC
Body Diode Forward Voltage Note	V _{F(S-D)}	I _F = 18 A, V _{GS} = 0 V		0.9	1.5	V
Reverse Recovery Time	t _{rr}	I _F = 18 A, V _{GS} = 0 V		56		ns
Reverse Recovery Charge	Q _{rr}	di/dt = 100 A/μs		146		nC

Note Pulsed

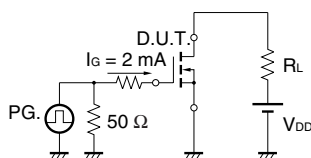
TEST CIRCUIT 1 AVALANCHE CAPABILITY



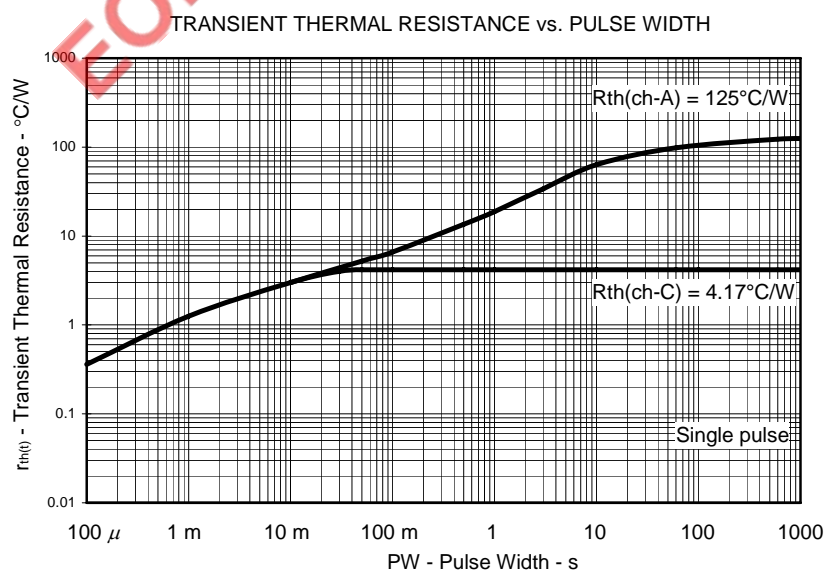
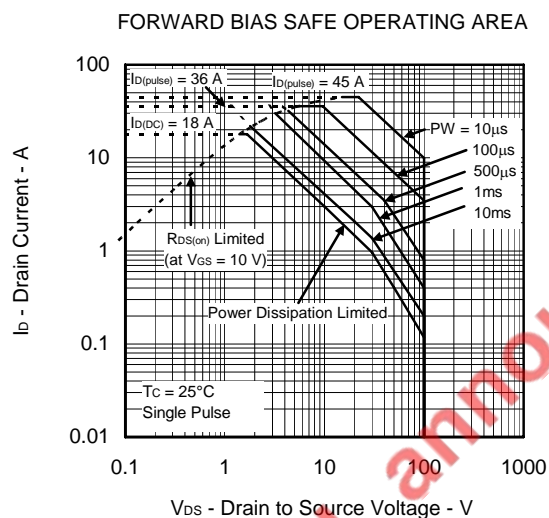
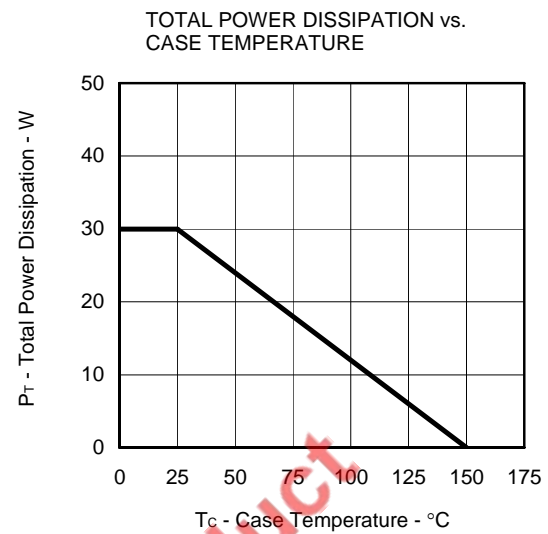
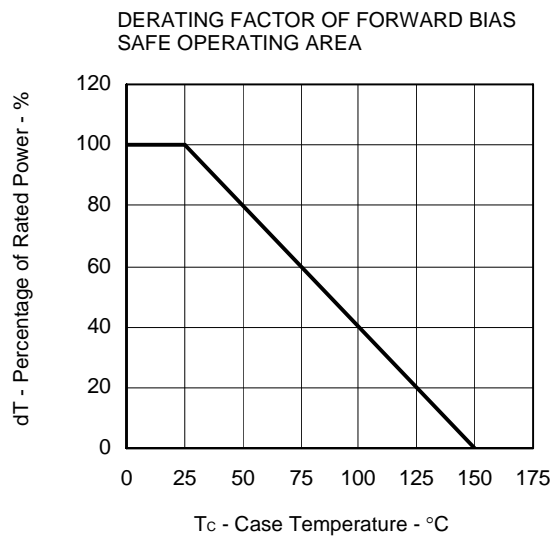
TEST CIRCUIT 2 SWITCHING TIME



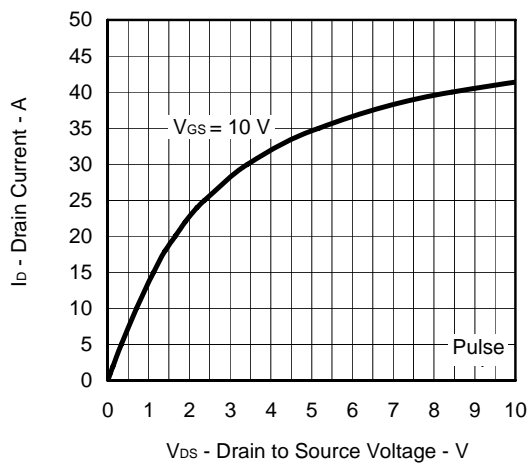
TEST CIRCUIT 3 GATE CHARGE



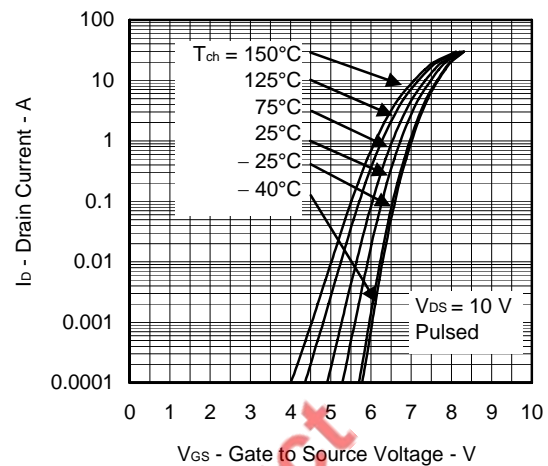
TYPICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$)



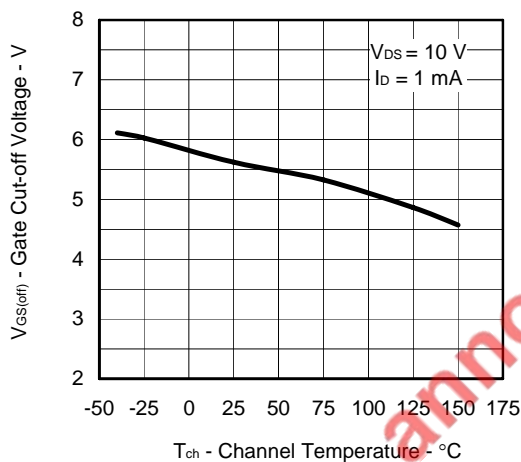
DRAIN CURRENT vs.
DRAIN TO SOURCE VOLTAGE



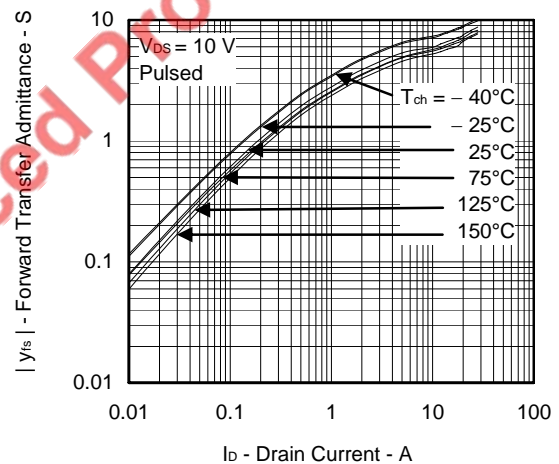
FORWARD TRANSFER CHARACTERISTICS



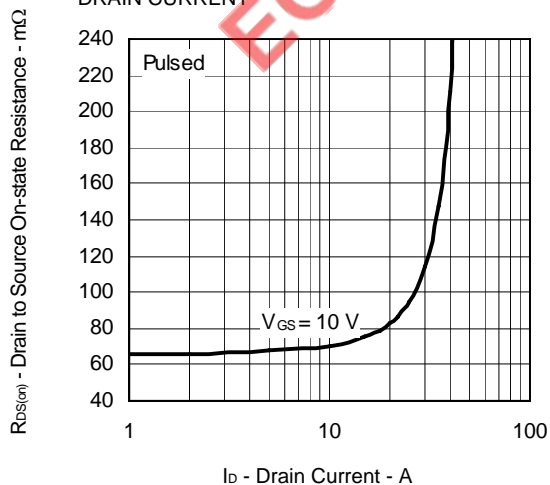
GATE CUT-OFF VOLTAGE vs.
CHANNEL TEMPERATURE



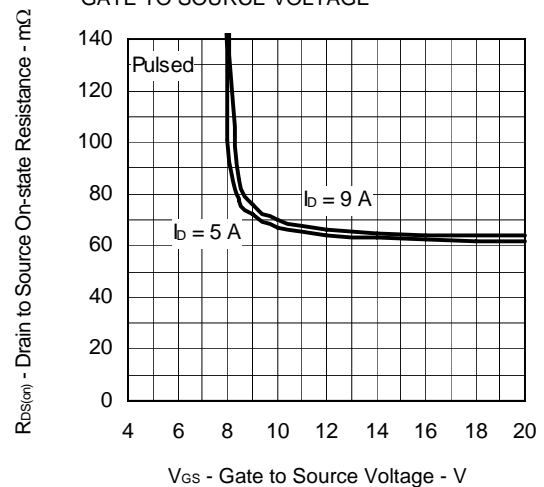
FORWARD TRANSFER ADMITTANCE vs.
DRAIN CURRENT



DRAIN TO SOURCE ON-STATE RESISTANCE vs.
DRAIN CURRENT

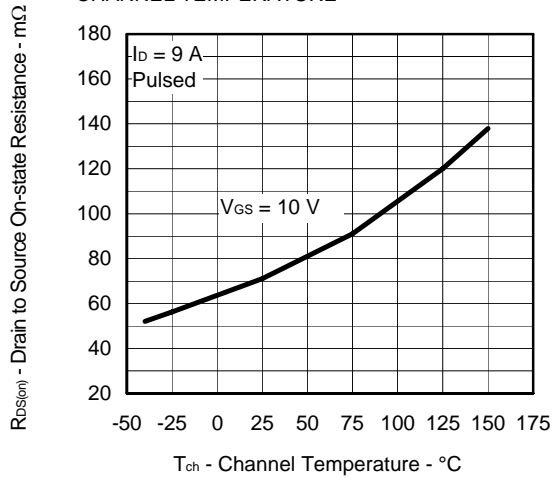


DRAIN TO SOURCE ON-STATE RESISTANCE vs.
GATE TO SOURCE VOLTAGE

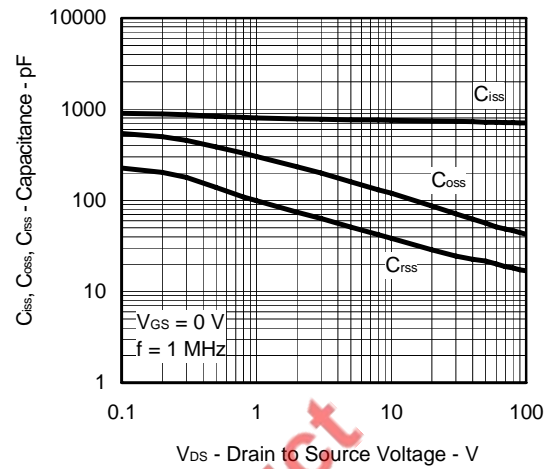


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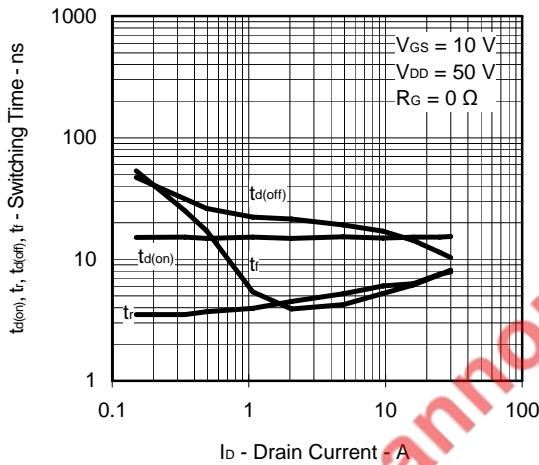
DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE



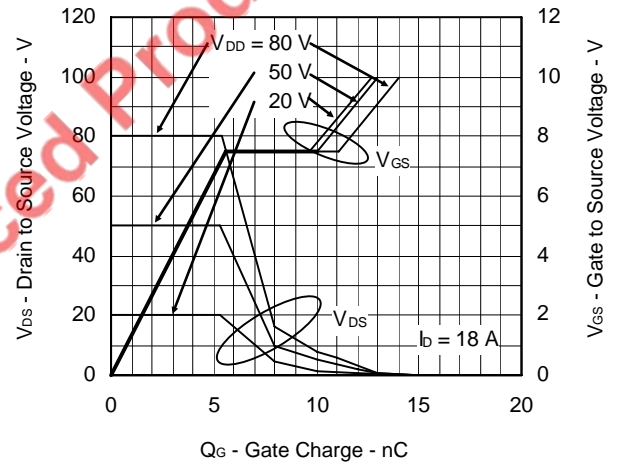
CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE



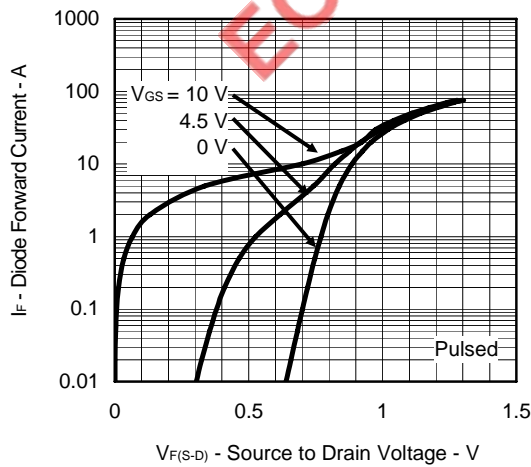
SWITCHING CHARACTERISTICS



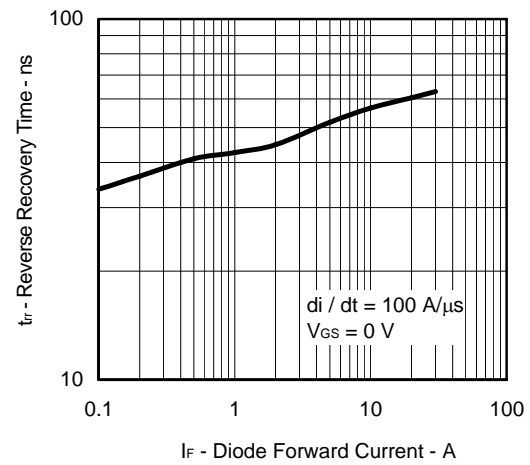
DYNAMIC INPUT/OUTPUT CHARACTERISTICS

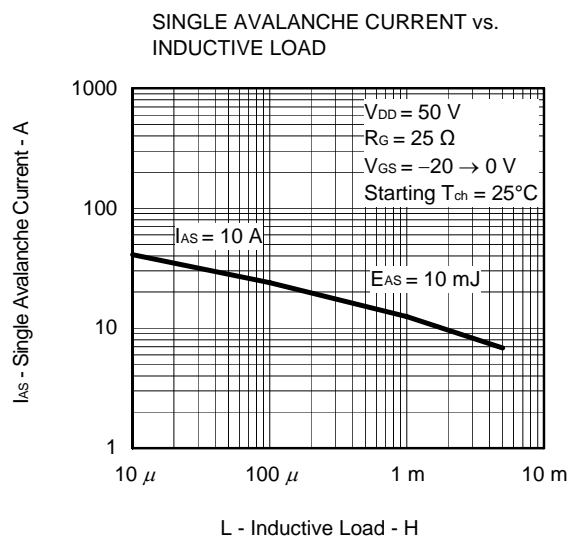


SOURCE TO DRAIN DIODE FORWARD VOLTAGE



REVERSE RECOVERY TIME vs. DIODE FORWARD CURRENT

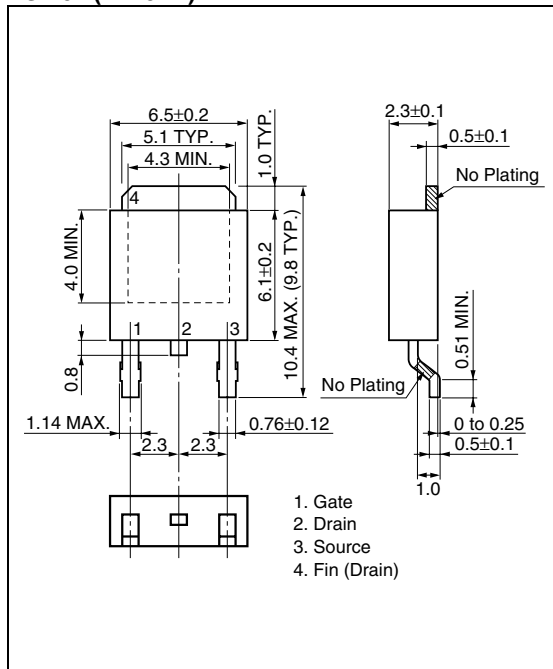




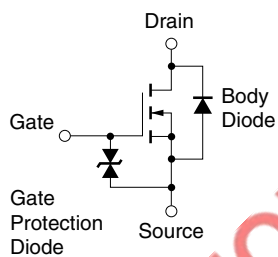
EOL announced Product

PACKAGE DRAWINGS (Unit: mm)

TO-252 (MP-3ZK)



EQUIVALENT CIRCUIT



Remark The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

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